

LUCRĂRI PUBLICATE

a.) Lucrări relevante incluse în format electronic în dosar

1. Jánó, R.; Pitică, D., *8 Channel Configurable Data Logger For Reliability Testing And Quality Assurance*, Proceedings of the 16th International Symposium for Design and Technology in Electronic Packaging (SIITME), Pitesti, Romania, 12-16 May 2010, pp. 255-258
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=5547302&contentType=Conference+Publications&queryText%3D8+Channel+Configurable+Data+Logger+For+Reliability+Testing+And+Quality+Assurance>)
2. Jánó, R.; Pitică, D., *Parameter Monitoring Of Electronic Circuits For Reliability Prediction And Failure Analysis*, Proceedings of the 34rd International Spring Seminar on Electronics Technology ISSE 2011, High Tatras, Slovakia, 11-15 May 2011, pp. 147-152
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6053568&contentType=Conference+Publications&queryText%3DParameter+Monitoring+Of+Electronic+Circuits+For+Reliability+Prediction+And+Failure+Analysis>)
3. Jánó, R.; Pitică, D., *Accelerated Ageing Tests For Predicting Capacitor Lifetimes*, Proceedings of the 17th International Symposium for Design and Technology in Electronic Packaging (SIITME), Timisoara, Romania, 20-23 October 2011, pp. 63-68
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6102687&contentType=Conference+Publications&queryText%3DAccelerated+Ageing+Tests+For+Predicting+Capacitor+Lifetimes>)
4. Jánó, R.; Pitică, D., *Investigating Capacitor Lifetimes Under Thermal Stress*, Proceedings of the 4th Electronics System Integration Technologies Conference (ESTC), 17-20 September 2012, pp. in press
5. Jánó, R.; Pitică, D., *Thermal Modeling Of Through Hole Capacitors*, Proceedings of the 18th International Symposium for Design and Technology in Electronic Packaging (SIITME), Alba Iulia, Romania, 25-28 October 2012, pp. in press
6. Jánó, R.; Pitică, D., *Accelerated Ageing Tests Of Aluminum Electrolytic Capacitors For Evaluating Lifetime Prediction Models*, Acta Tehnica Napocensis Electronics and Telecommunications, vol. 2/2012, July 2012, pp. 36-41
(<http://users.utcluj.ro/~atn/>)
7. Jánó, R.; Pitică, D.; Svasta, P.; Vărzaru, G., *Effects Of Reflow Soldering Methods On The Lifetime Of Capacitors*, Proceedings of the 35rd International Spring Seminar on Electronics Technology ISSE 2012, Bad Aussee, Austria, 9-13 May 2012, pp. 183-188
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6273135&contentType=Conference+Publications&queryText%3DEffects+Of+Reflow+Soldering+Methods+On+The+Lifetime+Of+Capacitors>)
8. Rajmond, J., Fodor, A., *Thermal management of embedded devices*, 36th International Spring Seminar on Electronics Technology (ISSE), 2013, ISSN 2161-2528, pp. 30-34
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6648210&queryText%3DRajmond>)
9. Jano, Rajmond; Fodor, Alexandra, *Soldering Profile Optimization for Through-Hole and Surface Mounted Ceramic Capacitors*, 37th International Spring Seminar on Electronics

- Technology (ISSE) - Advances in Electronic System Integration MAY 07-11, 2014 Dresden, GERMANY, pp. 174 - 179, ISBN 978-1-4799-4455-2
10. **Rajmond, Jano**; Alexandra, Fodor, *Educational tool for capacitor lifetime prediction*, Electronics Technology (ISSE), 2015 38th International Spring Seminar on, 6-10 May 2015, pp. 500 – 504

b.) Teza de doctorat

Lifetime investigations of capacitors under thermal and electrical stress – Investigatii privind durata de viață a condensatoarelor solicitate electric și termic
Universitatea Tehnică din Cluj-Napoca, 9 Noiembrie 2012

c.) Cărți publicate la edituri recunoscute

Rajmond JÁNÓ, Gabriel CHINDRIȘ, *Hardware and Software Testing Principles - Hands-on Training Guide*, Editura Mediamira, Cluj-Napoca, 2017 ISBN: 978-973-713-345-8

d.) Lucrări de laborator

1. Applied Informatics: Networking concepts
2. Applied Informatics: Microsoft Word 2016
3. Applied Informatics: Microsoft Excel 2016

e.) Publicații în extenso, apărute în lucrări ale principalelor conferințe internaționale de specialitate

1. **Jano Rajmond**, Gabriel Chindris, *Intelligent Human Interface Device*, IEEE 15th International Symposium for Design and Technology in Packaging (SIITME), 2009, Gyor, Hungary
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=5407358&contentType=Conference+Publications&queryText%3DIntelligent+Human+Interface+Device>)
2. **Jánó, R.**; Pitică, D., *8 Channel Configurable Data Logger For Reliability Testing And Quality Assurance*, Proceedings of the 16th International Symposium for Design and Technology in Electronic Packaging (SIITME), Pitesti, Romania, 12-16 May 2010, pp. 255-258
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=5547302&contentType=Conference+Publications&queryText%3D8+Channel+Configurable+Data+Logger+For+Reliability+Testing+And+Quality+Assurance>)
3. **Jánó, R.**; Pitică, D., *Data Logger For Signal Analysis And Failure Prediction*, Proceedings of the 33rd International Spring Seminar on Electronics Technology ISSE 2010, Warsaw, Poland, 23-26 September 2010, pp. 263-266
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=5650787&contentType=Conference+Publications&queryText%3DData+Logger+For+Signal+Analysis+And+Failure+Prediction>)
4. **Jánó, R.**; Pitică, D., *Parameter Monitoring Of Electronic Circuits For Reliability Prediction And Failure Analysis*, Proceedings of the 34rd International Spring Seminar on Electronics Technology ISSE 2011, High Tatras, Slovakia, 11-15 May 2011, pp. 147-152

- (<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6053568&contentType=Conference+Publications&queryText%3DParameter+Monitoring+Of+Electronic+Circuits+For+Reliability+Prediction+And+Failure+Analysis>)
5. Jánó, R.; Pitică, D., *Accelerated Ageing Tests For Predicting Capacitor Lifetimes*, Proceedings of the 17th International Symposium for Design and Technology in Electronic Packaging (SIITME), Timisoara, Romania, 20-23 October 2011, pp. 63-68
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6102687&contentType=Conference+Publications&queryText%3DAccelerated+Ageing+Tests+For+Predicting+Capacitor+Lifetimes>)
 6. Jánó, R.; Pitică, D., *Investigating Capacitor Lifetimes Under Thermal Stress*, Proceedings of the 4th Electronics System Integration Technologies Conference (ESTC), 17-20 September 2012, pp. in press
 7. Jánó, R.; Pitică, D., *Thermal Modeling Of Through Hole Capacitors*, Proceedings of the 18th International Symposium for Design and Technology in Electronic Packaging (SIITME), Alba Iulia, Romania, 25-28 October 2012, pp. in press
 8. Jánó, R.; Pitică, D., *Accelerated Ageing Tests Of Aluminum Electrolytic Capacitors For Evaluating Lifetime Prediction Models*, Acta Tehnica Napocensis Electronics and Telecommunications, vol. 2/2012, July 2012, pp. 36-41
(<http://users.utcluj.ro/~atn/>)
 9. Jánó, R.; Pitică, D., *Capacitor Lifetime Investigations*, Scientific Communications Session (SICOM), Cluj-Napoca, Romania, June 2012
 10. Jánó, R.; Pitică, D.; Svasta, P.; Vărzaru, G., *Effects Of Reflow Soldering Methods On The Lifetime Of Capacitors*, Proceedings of the 35rd International Spring Seminar on Electronics Technology ISSE 2012, Bad Aussee, Austria, 9-13 May 2012, pp. 183-188
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6273135&contentType=Conference+Publications&queryText%3DEffects+Of+Reflow+Soldering+Methods+On+The+Lifetime+Of+Capacitors>)
 11. Jano Rajmond, Todor Vlad, Dabacan Mircea, Bot Monica, *An Analysis of the Impact a Complete Virtual Laboratory has on the Learning Process*, Remote Engineering and Virtual Instrumentation, 2011, Brasov, Romania
 12. Vlad, T., Pitica, D., Rajmond, J., *Implementation of interactive communicational elements on e-learning educational platforms*, 18th International Symposium for Design and Technology in Electronic Packaging (SIITME), ISBN 978-1-4673-4757-0, pp. 347-350
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6384406&queryText%3DRajmond>)
 13. Vlad, T., Pitica, D., Man, L., Rajmond, J., *Optimized methods for theoretical and practical training*, 35th International Spring Seminar on Electronics Technology (ISSE), ISBN 978-1-4673-2241-6, pp. 459-464
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6273146&queryText%3DRajmond>)
 14. Rajmond, J., Fodor, A., *Thermal management of embedded devices*, 36th International Spring Seminar on Electronics Technology (ISSE), 2013, ISSN 2161-2528, pp. 30-34
(<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6648210&queryText%3DRajmond>)
 15. Fodor Alexandra, Jánó Rajmond, *Thermal Modelling of IC Packages*, Proceedings of the 18th International Symposium for Design and Technology in Electronic Packaging (SIITME), 2013, pp. 149-152

16. **Jano Rajmond**, Gabriel Chindris, *Intelligent Human Interface Device*, Novice Insights in Electronics, 2010, Cluj-Napoca, Romania
17. O. Gui, T. M. Pătăraș, **R. Jano**, Th. Mureșan, O.M. Gui, *Virtual Instrumentation and Data Acquisition in Scientific Investigation of Artworks from the National Cultural Heritage*, IEEE 15th International Symposium for Design and Technology in Packaging (SIITME), 2009, Gyor, Hungary
18. O. Gui, T. M. Pătăraș, **R. Jánó**, Th. Mureșan, O.M. Gui, *Aspecte referitoare la instrumentația virtuală și achiziția de date în investigarea științifică a operelor de artă din patrimoniul cultural*, Conferința internațională MATCONS 2009 – Materie și materiale în/pentru restaurarea – conservarea patrimoniului, 15-19 septembrie, Craiova, România.
19. **Jano R.**, T. M. Pătăraș, O. Gui, Th. Mureșan, D. Ienei, O. M. Gui, *Application of Virtual Instrumentation Technology in Scientific Investigation of Artworks From The National Cultural Heritage*, Proc. of the 6th National Conference of Virtual Instrumentation, CNIV 2009, 25 May, Brașov, Edit. BREN, București, pp.24-28.
20. O. Gui, T.M. Pătăraș, **Jano R.**, Th. Mureșan, D. Ienei, O.M. Gui, Interdisciplinary Curricula Development (I): Application of Virtual Instrumentation Technology in Scientific Investigation of Artworks from the Cultural Heritage, Proc. of the 4th
21. Fodor, Alexandra; **Jano, Rajmond**; Pitica, Dan, *Thermal Influences on IC Packages During Manual Soldering Process*, 37th International Spring Seminar on Electronics Technology (ISSE) - Advances in Electronic System Integration MAY 07-11, 2014 Dresden, GERMANY, pp. 54 - 57, ISBN 978-1-4799-4455-2
22. **Rajmond, J.**, Fodor, A., *Thermal management of embedded devices*, 36th International Spring Seminar on Electronics Technology (ISSE), 2013, ISSN 2161-2528, pp. 30-34 (<http://ieeexplore.ieee.org/xpl/articleDetails.jsp?tp=&arnumber=6648210&queryText%3DRajmond>)
23. **Jano, Rajmond**; Fodor, Alexandra, *Soldering Profile Optimization for Through-Hole and Surface Mounted Ceramic Capacitors*, 37th International Spring Seminar on Electronics Technology (ISSE) - Advances in Electronic System Integration MAY 07-11, 2014 Dresden, GERMANY, pp. 174 - 179, ISBN 978-1-4799-4455-2
24. Alexandra, Fodor; **Rajmond, Jano**; Dan, Pitica, *Flow Simulations for Component Spacing Optimization on PCB Boards*, 20th IEEE International Symposium on Design and Technology in Electronic Packaging (SIITME) Location: Bucharest, ROMANIA Date: OCT 23-26, 2014, ISBN:978-1-4799-6962-3
25. Fodor, Alexandra; **Jano, Rajmond**; Pitica, Dan, *Component placement optimizations on PCBs for improved thermal behaviour*; Electronics Technology (ISSE), 2015 38th International Spring Seminar on, 6-10 May 2015, pp. 114 – 117
26. **Rajmond, Jano**; Alexandra, Fodor, *Educational tool for capacitor lifetime prediction*, Electronics Technology (ISSE), 2015 38th International Spring Seminar on, 6-10 May 2015, pp. 500 – 504
27. Alexandra, Fodor; Gabriel, Chindris; **Rajmond, Jano**; Dan, Pitica; *Guidelines on thermal management solutions for modern packaging technologies - a review*, Design and Technology in Electronic Packaging (SIITME), 2015 IEEE 21st International Symposium for, Brasov, 2015, pp. 41-44.
28. **R. Jánó**, A. Fodor and A. I. Ilieș, "Simulation and educational tool for fault modelling in logic circuits," 2016 39th International Spring Seminar on Electronics Technology (ISSE), Pilsen, 2016, pp. 476-479.

29. A. I. Ilieș, R. Jánó and G. Chindriș, "Thermal management of System-on-Chip devices used in satellite systems under low temperature conditions," 2016 39th International Spring Seminar on Electronics Technology (ISSE), Pilsen, 2016, pp. 91-96.
30. A. Fodor, G. Chindris, D. Pitica and R. Jano, "Task allocation for thermal optimization in multicore systems," 2016 IEEE 12th International Conference on Intelligent Computer Communication and Processing (ICCP), Cluj-Napoca, 2016, pp. 349-352.
31. A. Miclăuș, R. Jánó and G. Chindriș, "Implementation of a car model for indirect tire pressure monitoring system," 2016 39th International Spring Seminar on Electronics Technology (ISSE), Pilsen, 2016, pp. 316-321.

Listă contracte de cercetare

2011/01/01 – 2011/12/31

Contract extern TEMIC 22379/08.11.2006

2012/01/01 – 2013/06/01

„Development and maintenance of a SIL/HIL testing model for automotive ECU”

2013/06/01 – prezent

„Development and maintenance of a SIL/HIL testing model for automotive ECU”